ACCRETECH

W-GM-6200

Wafer Edge Grinding Machine

- Wafer Size Φ 450 mm
- Best Seller Machine W-GM-Series
- Improve the Space Efficiency by the Compact Design
- Highly Accurate Grinding by the Synchronized X, Y, θ Support Control
- Easy Operation by Touch Panel
- Automatic feed-back of processing result will be given

TOKYO SEIMITSU CO., LTD.

Specification of W-GM-6200

Basic Specification		
Wafer Size		ϕ 450mm
Wafer Thickness		0.6 to 1.3mm (Standard)
Wafer Type		Notch
Grinding Unit		2-stage
Periphery Grinding Wheel	OD (Groove)	ϕ 200mm
	OD (Periphery)	ϕ 202mm
	ID	ϕ 30mm
	Flange Thickness	20mm
Peripheral Speed of Periphery Grinding Wheel (ϕ 202)		2500m/min (Maximum)
Grinding Speed		Periphery and notch can be set individually
Periphery Grinding Spindle		Built in drive by inverter motor
Operation Panel		15”color LCD panel with touch sensor
Signal Tower		3-color Indicator
Dimensions		4250 (W) x 2900 (D) x 2600 (H) mm
Weight		Approx. 9000kg
Mechanical Specification		
Grinding Table X, Y, Z-axis	Resolution	1µm
Grinding Table θ-axis	Resolution	0.001°
	Driving System	DD Motor
Transfer Unit	Loading System	Chuck Loading (Upper Surface)
Cleaning Unit	Cleaning System	Spin Cleaning
	Drying System	Dry Air
Loader Unit	Type	Cassette Carrier Type
	Number of Cassette	4C(Standard)
Measuring Unit Specification		
Wafer Thickness Measurement	Resolution	1 µm
	Repeatability Accuracy	Within ±2 µm
	Measuring Type	Non Contact Type
Non-contact Alignment System	Type	Green LED System
	Resolution	1 µm
	Centering Accuracy	Within ±35 µm

ACCRETECH

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●We reserve the right to change the contents of this catalog,
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